

ESREF 2000, the 11th European Symposium on Reliability of Electron Devices and Failure Analysis will take place at Dresden, Germany from October 2nd - 6th, 2000.

This event will provide the European forum for the presentation of recent developments and future trends in quality and reliability assessment of micro-electronic material, devices and modules in their extending areas of application. All aspects of specification, technology, design and manufacturing advances, testing, control and analysis will be addressed.

The symposium has included the scope of the previous **EOBT** Conference, Electron and Optical Beam Testing.

Tutorials by experts will provide reviews and up-dates of selected topics of actual interest.

Invited papers will introduce into the main stream topics.

Workshops on subjects in progress will provide the opportunity for exchange of know-how.

Equipment demonstration has proven to be a valuable accompanying event which provides experience with advanced techniques and recent developments for testing and analysis.

internet: <http://www.vde.de/ESREF2000>

**Conference Venue** Hotel Westin Bellevue  
Dresden  
Germany

The choice of Dresden refers to the growing engagement of the area into advanced Semiconductor Technology as well to the opportunity for enjoying its historic and cultural value originating from the Royal Saxonian Era.

For more information please address the Conference Organization Secretariat

## SCOPE OF PAPERS / TECHNICAL PROGRAMME

### Reliability management of micro-electronic devices and power semiconductor modules

in development, test, manufacturing, application of  
- silicon devices, signal and power  
- compound semiconductors, SOI  
- micromechanical systems, sensors, MEMs  
- MCM, packaging and assemblies

### Technology and design

design for reliability, simulation, redundancy, thermal management, built-in self test, application specific challenges : high temperature applications , ..

### Control in manufacturing

critical parameters, yield and reliability, test, screening, reliability monitoring at wafer / product level, known good die, ...

### Qualification versus application

best practice qualification methods, design and use of test structures, field observation and analysis, ...

### Failure mechanisms

characterization, modelling of mechanisms:  
dielectric breakdown, metal migration, hot carrier degradation, contaminants' mechanisms, corrosion, mechanical fatigue  
ESD, EOS, latch-up, EMC, EMI effects

### Defect detection methods and case studies

case studies, characterization, localization, using e.g. electrical, thermal, optical, acoustical methods, signature analysis, navigation methods, ..

### Preparation and failure analysis techniques, case studies

sample preparation, constructional / failure analysis  
electron, ion, laser beam techniques, scanning probe microscopy

## SUBMISSION OF PAPERS

Deadlines:

Three page extended summary incl. figures **March 10th, 2000**

The title page shall include

- a five-lines abstract,
- the complete address, fax number and e-mail address of the first author,
- preference for oral or poster presentation.

Notification of acceptance to authors **May 10th, 2000**

Submission of the complete paper **June 10th, 2000**

Summaries and papers must be written in English. One original and the electronic file (WORD6 or 7) should be mailed to the Scientific Conference Secretariat

Request for Information / announcement of paper

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ESREF 2000

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ANNOUNCEMENT  
and 1st CALL FOR PAPERS

11 th EUROPEAN SYMPOSIUM  
RELIABILITY OF ELECTRON DEVICES, FAILURE  
PHYSICS AND ANALYSIS

DRESDEN - GERMANY  
2 - 6 OCTOBER 2000



internet: <http://www.vde.de/ESREF2000>

organized by  
ITG - Information Technology Society of VDE,  
WG Quality and Reliability of Integrated Circuits

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